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(54) LEAD FRAME

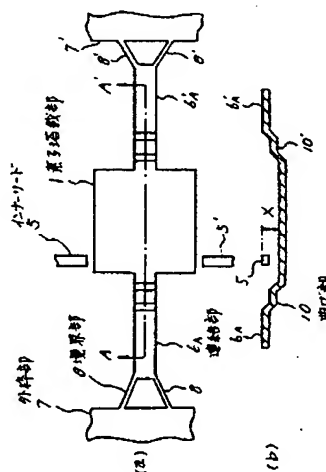
(57) Abstract:

PURPOSE: To prevent the deformation of the position of an element loading section at the time of the heating of an element manufacturing process, to obviate the generation of the trouble of the short circuit of a bonding wire and to improve the reliability of an integrated circuit device by forming a bent section at least two steps to a connecting section connecting the element loading section and an outer frame section.

CONSTITUTION: A lead frame has an element loading section 1, a plurality of inner leads 5 and 5' having predetermined stepped sections X with the element loading section 1 and connecting sections 6A and 6A' connecting the element loading section 1 to outer frame sections 7 and 7' and having bent sections 10 and 10' at two steps. Consequently, the bent sections 10 and 10' at two steps are shaped to the connecting sections 6A and 6A', thus dispersing stress generated due to the inhibition of thermal expansion and expansion to

the bent sections. Accordingly, stress is released and the displacement of the position of the element loading section 1 is prevented, thus obviating the generation of the defective short circuit of bonding wires.

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